A beamer tutorial

LayoutBeamer, from GenISys GmbH

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Beamer, or "LayoutBeamer" is a program which converts pattern shapes to machine-specific formats, chopping polygons into trapezoids, and cutting large patterns at exposure field boundaries. Patterns will be stitched together by writing each field, then moving the stage.

Many e-beam systems and mask writers can use the same pattern fracturing software, and so a company such as GeniSys can provide better support with a broader customer base than Vistec et al.

The main competitor is "Cats" from Synopsys, which has been the defacto standard (until recently), and is used on many e-beam writers. Cats is very mature and bug-free, but also very expensive.











3	new flow - Layout BEAMER	_ 🗆 🗙
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		7
Welcome to Layout BEAMER	Project Directory: /home/rooks/projects/cat	



The default settings are almost always the best choices.

The two things you will have to choose: beam step size and field size.

In **this** dialog box, "resolution" means "fracturing resolution". It should always equal the beam step size.

You should calculate the best beam step based on resist sensitivity and resolution requirements.

One way to do this is to use the EBPG calculator.

But really, you should have thought about the beam step long ago, before doing the CAD.

		Expo	ort EBPG		×
General	Advanced	Tool Exte	ent		
Format	Type 5000-	⊦ wide field	20 bit 50 MHz	-	
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Let's change the beam step to 0.004 microns (4 nm).

Make sure the "resolution" is also 0.004 microns. It may or may not change by itself.

Next switch to the "Advanced" tab.

		Exp	ort EBPO	G	<u>د</u>
General A	dvanced	Tool Ex	tent		
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Here the term "resolution" means the EBPG's bit size; that is, one DAC bit equals 1 nm. That's the default, and you should not change it.

It's unfortunate that Beamer uses the term "resolution" to mean two different things.

Now look at the "Mainfield Size". This is a subset of the maximum exposure field $(1 \text{ nm})(2^{20}) \approx 1 \text{ mm}$. Some folks call this the "block size", because the pattern will be chopped into blocks of this size.

The default size was 600 μ m, but Beamer changed it to 1000 μ m when you changed the step size. Why? Because it seemed like a good idea to someone, long ago.

Now you should change it to some sensible number, like... 600 μ m.

Export EBPG X
General Advanced Tool Extent
Mainfield Settings
Resolution [um] 0.001 MSF 4
Size [um] X 1000.000 Y 1000.000
Overlap [um] X 0.000 Y 0.000
Fixed View Layout Floating
O Manual by Region Layer
X Min [um] Y Min [um] X Max [um] Y Max [um] Delete
-Subfield Settings
Resolution [um] 0.0005 MSF 8
Size [um] X 4.000 Y 4.000
Scale Dose Range
Dose Correction for Small Trapezoids

	Export EBPG								
	General Advanced Tool Extent								
	Mainfield Settings								
Make sure that the field (block) size	Resolution [um] 0.001 💌 MSF 4								
is a multiple of the subfield size.	Size [um] X 1000.000 Y 1000.000								
Otherwise, the left-over	Overlap [um] X 0.000 Y 0.000								
the others, leading to subfield	I Fixed View Layout								
misplacement due to drift.	○ Floating								
	O Manual by Region Layer								
	X Min [um] Y Min [um] X Max [um] Y Max [um] Delete								
	Subfield Settings								
	Resolution [um] 0.0005 MSF 8								
	Size [um] X 4.000 Y 4.000								
	Scale Dose Range								
	Dose Correction for Small Trapezoids								

Thank goodness we can't change anything on the "tool" tab.

E	E	xport	EBPG	×
	General Advanced Tool E	Extent		
	Format Type 5000+ wi	ide fielo	d 20 bit 50 MHz	
	Format Version 1.40			
	Voltage [kV] 100			
	Mainfield Configuration			
	Number DAC Bits	20		
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	Maximum Mainfield [um]	1000.	00000	
	Subfield Configuration			
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	Maximum Subfield [um]	4.0000	00	
	Maximum MSF	512		
	<i>ф</i> <u>о</u> к	×	Cancel	

On the "extent" tab you may want to change the lower-left corner to control the field fracturing.

You should also pay attention to the upper-right corner, since the average of these coordinates will be the "chip center".

The "chip center" will be the reference point for placement and alignment in Vistec's exposure job software.

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Click on the play button to start the fracturing process. When that is done, click on the same spot to see the fractured pattern Choose the lower-left point and the block size so that stitching boundaries will avoid critical features. The sample stage will move at block boundaries, causing stitching errors of 15-20 nm.



Actually, you should think about field stitching while planning the design. You may have to go back to the CAD program and start over. Alternatively, try using the "floating field" option, which will let Beamer attempt to center isolated features inside exposure fields.

For some designs this can be very handy.

Export EBPG	
General Advanced Tool Extent	
Mainfield Settings	1
Resolution [um] 0.001 MSF 5	
Size [um] X 600.000 Y 600.000	
Overlap [um] X 0.000 Y 0.000	
Fixed	
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X Min [um] Y Min [um] X Max [um] Y Max [um] View Layout	
Delete	
Subfield Settings	
Resolution [um] 0.0005 T MSF 10	
Size [um] X 4.000 Y 4.000	
Scale Dose Bange	
Dose Correction for Small Trapezoids	
	-
₩ <u>O</u> K <u>X</u> Cancel	

Those are the three basic steps you always need:

Import Extract Export

But there are all sorts of other things you might need to do.

For example, suppose you need to crop the pattern. You'll find that you cannot simply set the lower-left and upper-right corners in the "export" box. Instead, you'll need an extra "extract" step.





click on "play" at the bottom to rerun the steps.

Then click there again to view the pattern.



Another important function is overlap removal, or "healing". Actually, healing and overlap removal are two things, but in practice you always want to heal the shapes (merge them) after removing overlaps.

If you remove overlaps and heal the pattern, any information about layers and datatypes will be lost. So... healing is not allowed, if you need to assign doses.

How do you assign doses?



When you pull down the list box under "layer", you should see a list of all the layers and datatypes in your pattern.

They are listed as

layer (datatype)

In this pattern, layer 0 includes shapes with datatypes 0, 1, 2.

The EBPG accepts RELATIVE dose values. Other e-beam writers let you create a dose variable that can be assigned at run-time. Not the EBPG.

(The "assignment type" choice seems to be irrelevant for the EBPG.)



Checking the GPF file with Cview



					Cview v04_09: Copyright © Vistec Lithography (20	10)
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Same zooming action: UL to LR zooms in, LR to UL zooms out

Hover over a shape and press the Ctrl key to reveal details of a shape.





Use pattern \rightarrow header to reveal all the gory details.

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